

Title (en)

AUTODEPOSITION EMULSION FOR SELECTIVELY PROTECTING METALLIC SURFACES

Publication

EP 0468002 A4 19950809 (EN)

Application

EP 91901406 A 19901214

Priority

- US 45165889 A 19891215
- US 45168089 A 19891215
- US 62136190 A 19901207

Abstract (en)

[origin: WO9108840A1] Generally, the invention relates to the technical field of autodeposition emulsions and methods of selectively coating metallic surfaces therewith, especially those surfaces which are subjected to etchant baths as the surfaces are being processed as circuit traces for electronic circuit boards. A coating of resin and photoactive functionality is autodeposited from an emulsion onto a metallic substrate in order to selectively protect the substrate from corrosive environments such as etchant processes. An acid and oxidizing agent are included in the emulsion so that when the substrate is immersed in the emulsion the resin and photoactive functionality autodeposits. The resulting coating can be exposed to actinic radiation in an image-wise fashion and developed in an alkaline solution to develop the image created. In instances where the emulsion and process are used to make circuit boards, the metallic surface uncovered during developing is then etched away, leaving only the coated sections of the surface. The resulting coated surfaces will be the circuit traces of the circuit board.

IPC 1-7

B05D 1/0; **G03C 1/0**; **G03C 1/0**

IPC 8 full level

B05D 7/14 (2006.01); **G03F 7/16** (2006.01); **H05K 3/06** (2006.01); **B05D 3/06** (2006.01)

CPC (source: EP)

B05D 7/142 (2013.01); **G03F 7/16** (2013.01); **H05K 3/064** (2013.01); **B05D 3/067** (2013.01); **B05D 7/144** (2013.01); **H05K 2203/0759** (2013.01); **H05K 2203/0796** (2013.01)

Citation (search report)

- No further relevant documents disclosed
- See references of WO 9108840A1

Cited by

EP2468869A1

Designated contracting state (EPC)

AT BE CH DE DK ES FR GB GR IT LI LU NL SE

DOCDB simple family (publication)

WO 9108840 A1 19910627; AU 631719 B2 19921203; AU 7033891 A 19910718; CA 2051400 A1 19910616; CN 1030739 C 19960117; CN 1054836 A 19910925; EP 0468002 A1 19920129; EP 0468002 A4 19950809

DOCDB simple family (application)

US 9007468 W 19901214; AU 7033891 A 19901214; CA 2051400 A 19901214; CN 90110428 A 19901215; EP 91901406 A 19901214